



Volume I

Aberrations—Electro

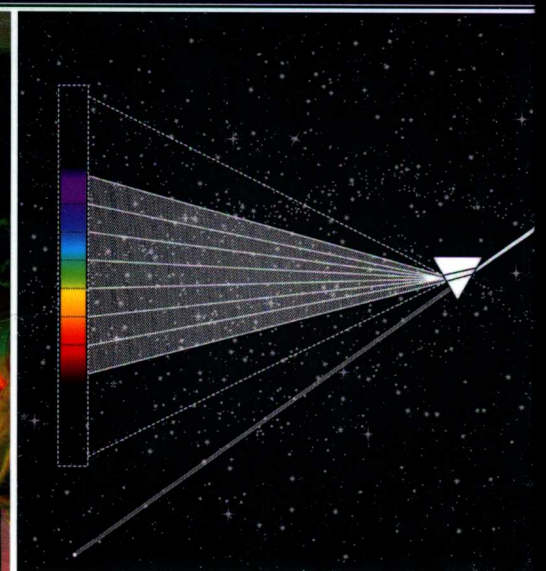
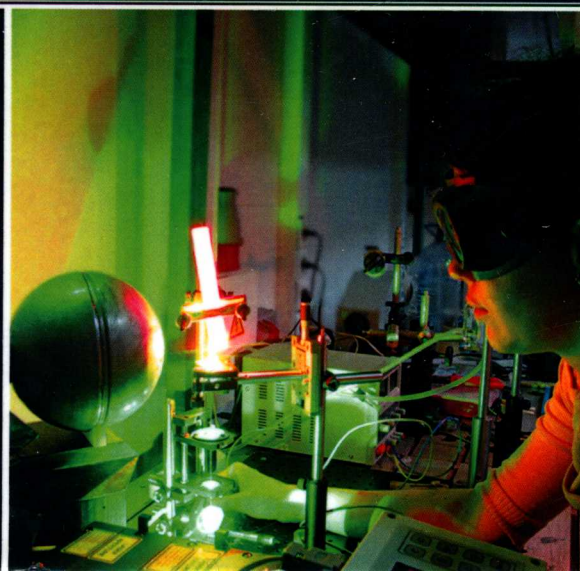
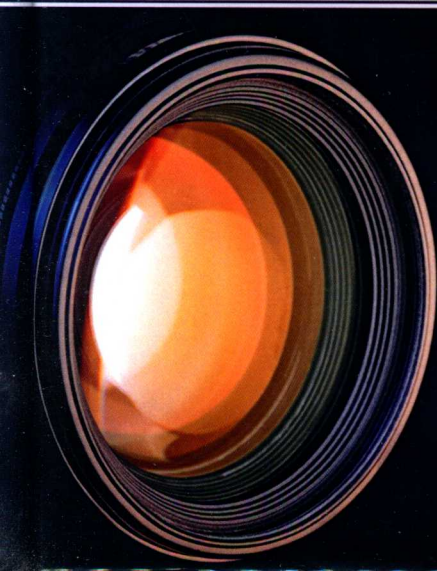


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Encyclopedia of
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PHOTONIC
ENGINEERING**
SECOND EDITION

Edited by

Craig Hoffman • Ronald Driggers

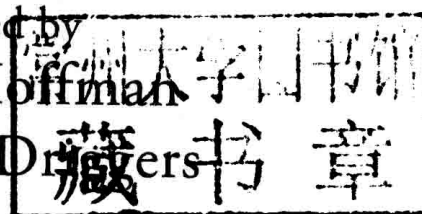


Encyclopedia of OPTICAL AND PHOTONIC ENGINEERING

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